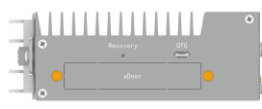




特点:

- 支持 NVIDIA® Jetson TMSO-DIMM 连接器核心板
- 高性能的 AI 控制器, 最高可达 100TOPS 算力
- 默认板载 3 个千兆网络、4 个 USB3.0
- 可选 16bitDIO、2 个 RS232/RS485 可配置 COM
- 支持 5G/4G/WiFi 功能扩展
- 支持 DC 12~28V 宽压输入
- 无风扇超紧凑设计, 全金属高强度机身
- 支持桌面式、DIN 安装



远程管理



状态监控



远程运维

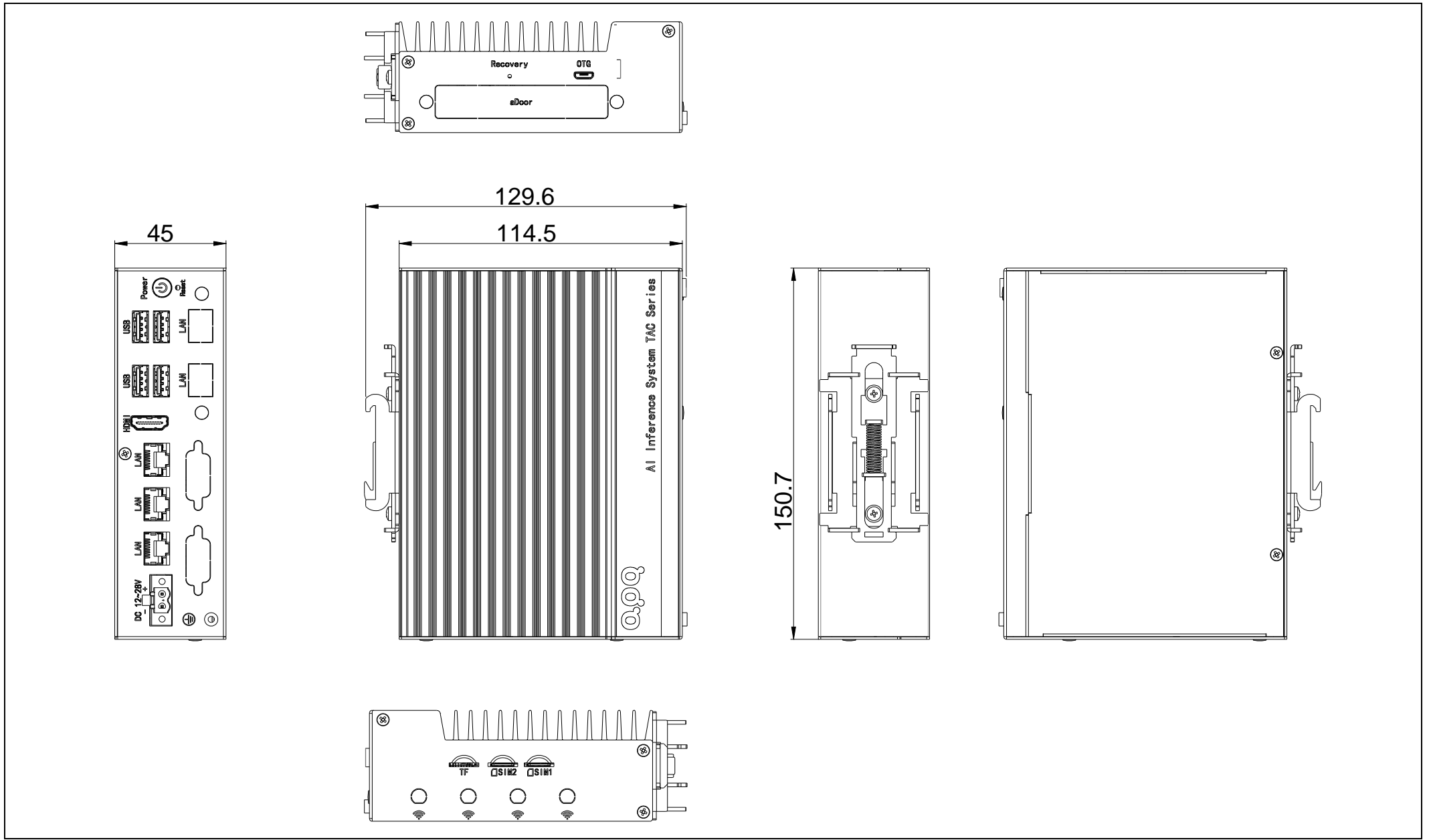


安全控制

产品规格

Model	TAC-3000					
Processor System	SOM	<b>Nano</b>	<b>TX2 NX</b>	<b>Xavier NX</b>	<b>Xavier NX 16GB</b>	
	AI Performance	472 GFLOPS	1.33 TFLOPS	21 TOPS		
	GPU	128-core NVIDIA Maxwell™ architecture GPU	256-core NVIDIA Pascal™ architecture GPU	384-core NVIDIA Volta™ architecture GPU with 48 Tensor Cores		
	GPU Max Frequency	921MHz	1.3 GHz	1100 MHz		
	CPU	Quad-core ARM® Cortex®-A57 MPCore processor	Dual-core NVIDIA Denver™ 2 64-bit CPU and quad-core Arm® Cortex®-A57 MPCore processor	6-core NVIDIA Carmel Arm® v8.2 64-bit CPU 6MB L2 + 4MB L3		
	CPU Max Frequency	1.43GHz	Denver 2: 2 GHz Cortex-A57: 2 GHz	1.9 GHz		
	Memory	4GB 64-bit LPDDR4 25.6GB/s	4GB 128-bit LPDDR4 51.2GB/s	8GB 128-bit LPDDR4x 59.7GB/s	16GB 128-bit LPDDR4x 59.7GB/s	
TDP	5W-10W	7.5W - 15W	10W - 20W			
Processor System	SOM	<b>Orin Nano 4GB</b>	<b>Orin Nano 8GB</b>	<b>Orin NX 8GB</b>	<b>Orin NX 16GB</b>	
	AI Performance	20 TOPS	40 TOPS	70 TOPS	100 TOPS	
	GPU	512-core NVIDIA Ampere architecture GPU with 16 Tensor Cores	1024-core NVIDIA Ampere architecture GPU with 32 Tensor Cores	1024-core NVIDIA Ampere architecture GPU with 32 Tensor Cores		
	GPU Max Frequency	625 MHz	765 MHz	918 MHz		
	CPU	6-core Arm® Cortex® A78AE v8.2 64-bit CPU 1.5MB L2 + 4MB L3		6-core Arm® Cortex® A78AE v8.2 64-bit CPU 1.5MB L2 + 4MB L3	8-core Arm® Cortex® A78AE v8.2 64-bit CPU 2MB L2 + 4MB L3	
	CPU Max Frequency	1.5 GHz		2 GHz		
	Memory	4GB 64-bit LPDDR5 34 GB/s	8GB 128-bit LPDDR5 68 GB/s	8GB 128-bit LPDDR5 102.4 GB/s	16GB 128-bit LPDDR5 102.4 GB/s	
TDP	7W - 10W	7W - 15W	10W - 20W	10W - 25W		
Ethernet	Controller	1 * GBE LAN Chip (LAN signal from System-on-Module), 10/100/1000 Mbps 2 * Intel® I210-AT, 10/100/1000 Mbps				
Storage	eMMC	16GB eMMC 5.1 (Orin Nano and Orin NX SOMs do not support eMMC)				
	M.2	1 * M.2 Key-M (NVMe SSD, 2280) (Orin Nano and Orin NX SOMs is PCIe x4 signal, while other SOMs is PCIe x1 signal)				
Expansion Slots	TF Slot	1 * TF Card Slot (Orin Nano and Orin NX SOMs do not support TF Card)				
	Mini PCIe	1 * Mini PCIe Slot (PCIe x1+USB 2.0, with 1 * Nano SIM Card) (Nano SOM do not have PCIe x1 signal)				
Front I/O	M.2	1 * M.2 Key-B Slot (USB 3.0, with 1 * Nano SIM Card, 3052)				
	Ethernet	2 * RJ45				
	USB	4 * USB3.0 (Type-A)				
	Display	1 * HDMI: Resolution up to 4K @ 60Hz				
Side I/O	Button	1 * Power Button + Power LED 1 * System Reset Button				
	USB	1 * USB 2.0 (Micro USB, OTG)				
	Button	1 * Recovery Button				
	Antenna	4 * Antenna hole				
Internal I/O	SIM	2 * Nano SIM				
	Serial	2 * RS232/RS485 (COM1/2, wafer, Jumper Switch) 1 * RS232/TTL (COM3, wafer, Jumper Switch)				
	PWRBT	1 * Power Button (wafer)				
	PWRLED	1 * Power LED (wafer)				
	Audio	1 * Audio (Line-Out + MIC, wafer) 1 * Amplifier, 3-W (per channel) into a 4-Ω Loads (wafer)				
	GPIO	1 * 16 bits DIO (8xDI and 8xDO, wafer)				
	CAN Bus	1 * CAN (wafer)				
Power Supply	FAN	1 * CPU FAN (wafer)				
	Type	DC, AT				
	Power Input Voltage	12~28V DC				
	Connector	Terminal block, 2Pin, P=5.00/5.08				
OS Support	RTC Battery	CR2032 Coin Cell				
	Linux	Nano/TX2 NX/Xavier NX: JetPack 4.6.3 Orin Nano/Orin NX: JetPack 5.3.1				
Mechanical	Enclosure Material	Radiator: Aluminum alloy, Box: SGCC				
	Dimensions	150.7mm(L) * 144.5mm(W) * 45mm(H)				
	Mounting	Desktop、DIN-rail				
Environment	Heat Dissipation System	Fan less design				
	Operating Temperature	-20~60℃ with 0.7 m/s airflow				
	Storage Temperature	-40~80℃				
	Relative Humidity	10 to 95% (non-condensing)				
	Vibration	3Grms@5~500Hz, random, 1hr/axis (IEC 60068-2-64)				
Shock	10G, half sine, 11ms (IEC 60068-2-27)					

产品尺寸



产品 IO

